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FDV303N Digital FET, N-Channel

General Description

These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance at low gate drive conditions. This device is designed especially for application in battery circuits using either one lithium or three cadmium or NMH cells. It can be used as an inverter or for high-efficiency miniature discrete DC/DC conversion in compact portable electronic devices like cellular phones and pagers. This device has excellent on-state resistance even at gate drive voltages as low as 2.5 volts.

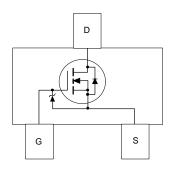
Features

- $\begin{tabular}{ll} \blacksquare & 25 \ V, \, 0.68 \ A \ continuous, \, 2 \ A \ Peak. \\ & R_{\rm DS(ON)} = 0.45 \ \Omega \ @ \ V_{\rm GS} = 4.5 \ V \\ & R_{\rm DS(ON)} = 0.6 \ \Omega \ @ \ V_{\rm GS} = 2.7 \ V. \\ \end{tabular}$
- Very low level gate drive requirements allowing direct operation in 3V circuits. V_{GS(th)} < 1V.
- Gate-Source Zener for ESD ruggedness.>6kV Human Body Model
- Compact industry standard SOT-23 surface mount package.
- Alternative to TN0200T and TN0201T.



Mark:303





Absolute Maximum Ratings $T_A = 25^{\circ}\text{C}$ unless other wise noted

Symbol	Parameter	FDV303N	Units
V _{DSS}	Drain-Source Voltage, Power Supply Voltage	25	V
V_{GSS}	Gate-Source Voltage, V _{IN}	8	V
I _D	Drain/Output Current - Continuous	0.68	А
	- Pulsed	2	
P_{D}	Maximum Power Dissipation	0.35	W
T_{J},T_{STG}	Operating and Storage Temperature Range	-55 to 150	.€
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)	6.0	kV
THERMA	L CHARACTERISTICS		<u>.</u>
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAR	ACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		25			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C			26		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, \ V_{GS} = 0 \text{ V}$				1	μA
			$T_J = 55^{\circ}C$			10	μA
I _{GSS}	Gate - Body Leakage Current	$V_{GS} = 8 \text{ V}, \ V_{DS} = 0 \text{ V}$	•			100	nA
ON CHARA	CTERISTICS (Note)	<u> </u>				•	
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C			-2.6		mV/°C
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		0.65	0.8	1	V
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$			0.33	0.45	Ω
- (-)			T _J =125°C		0.52	0.8	
		$V_{GS} = 2.7 \text{ V}, I_{D} = 0.2 \text{ A}$			0.44	0.6	
I _{D(ON)}	On-State Drain Current	$V_{GS} = 2.7 \text{ V}, \ V_{DS} = 5 \text{ V}$		0.5			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 0.5 \text{ A}$			1.45		S
DYNAMIC (CHARACTERISTICS	•					•
C _{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, \ V_{GS} = 0 \text{ V},$ f = 1.0 MHz			50		pF
C _{oss}	Output Capacitance				28		pF
C _{rss}	Reverse Transfer Capacitance				9		pF
SWITCHING	CHARACTERISTICS (Note)						
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, \ I_{D} = 0.5 \text{ A},$ $V_{GS} = 4.5 \text{ V}, \ R_{GEN} = 50 \Omega$			3	6	ns
t,	Turn - On Rise Time				8.5	18	ns
t _{D(off)}	Turn - Off Delay Time				17	30	ns
t _r	Turn - Off Fall Time				13	25	ns
Q_g	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_{D} = 0.5 \text{ A},$ $V_{GS} = 4.5 \text{ V}$			1.64	2.3	nC
Q_{gs}	Gate-Source Charge				0.38		nC
Q_{gd}	Gate-Drain Charge				0.45		nC
DRAIN-SO	URCE DIODE CHARACTERISTICS AND M	AXIMUM RATINGS					
l _s	Maximum Continuous Drain-Source Diode Forward Current					0.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.5 \text{ A} \text{ (Note)}$			0.83	1.2	V

Note:

Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2.0\%$.

Typical Electrical Characteristics

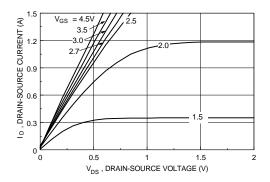


Figure 1. On-Region Characteristics.

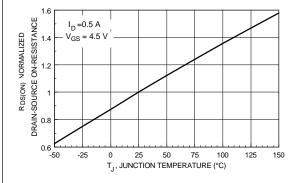


Figure 3. On-Resistance Variation with Temperature.

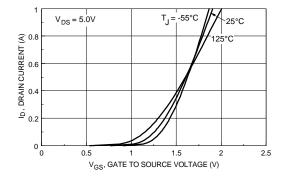


Figure 5. Transfer Characteristics.

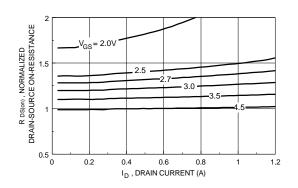


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

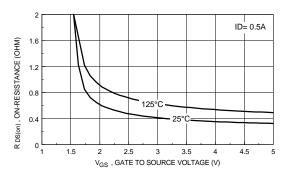


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

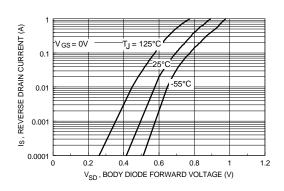


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical And Thermal Characteristics

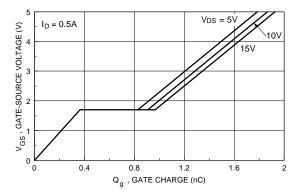


Figure 7. Gate Charge Characteristics.

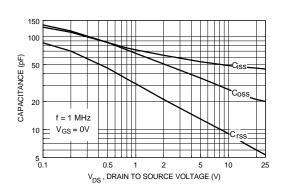


Figure 8. Capacitance Characteristics.

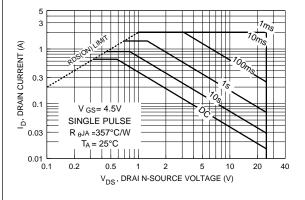


Figure 9. Maximum Safe Operating Area.

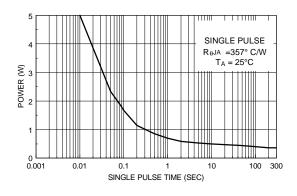


Figure 10. Single Pulse Maximum Power Dissipation.

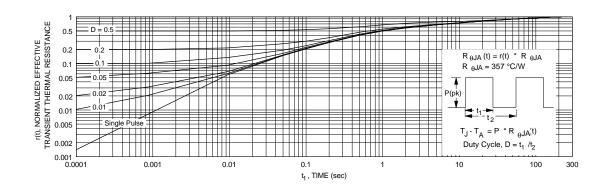
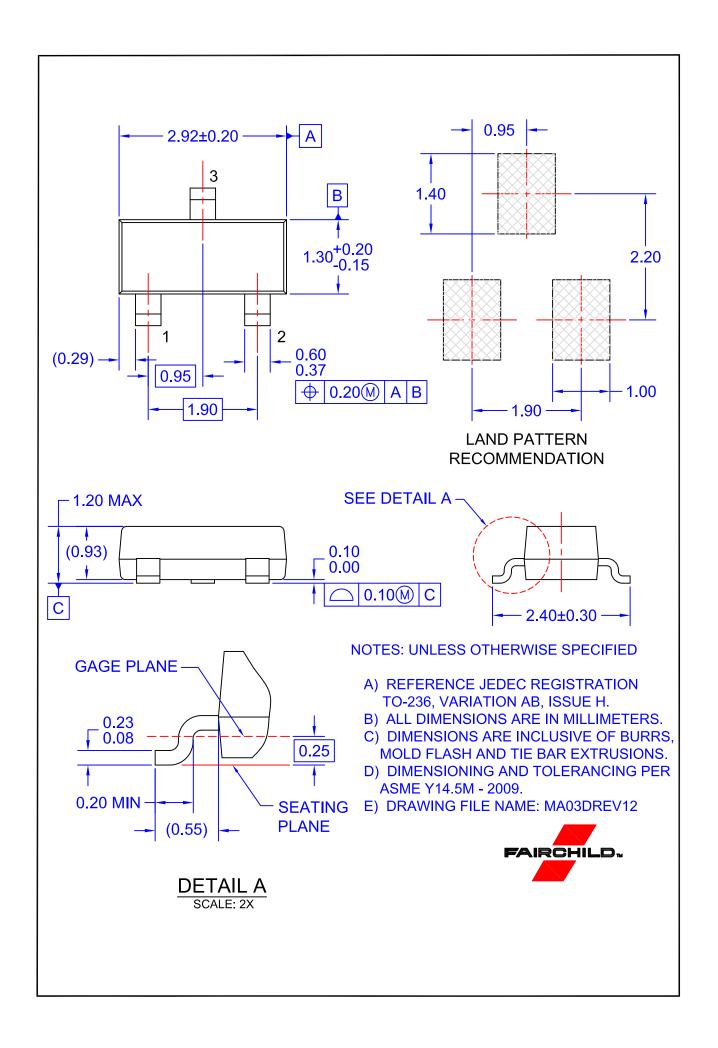


Figure 11. Transient Thermal Response Curve.



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